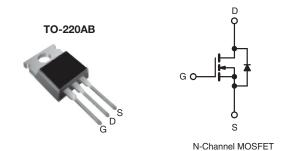


COMPLIANT

### Power MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	10	100			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = 5.0 V	0.16			
Q <sub>g</sub> (Max.) (nC)	28				
Q <sub>gs</sub> (nC)	3.8				
Q <sub>gd</sub> (nC)	14				
Configuration	Single				



### **FEATURES**

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- · Logic-Level Gate Drive
- $R_{DS(on)}$  Specified at  $V_{GS} = 4 V$  and 5 V
- 175 °C Operating Temperature
- Fast Switching
- · Ease of Paralleling
- Compliant to RoHS Directive 2002/95/EC

#### **DESCRIPTION**

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRL530PbF
Lead (PD)-life	SiHL530-E3
SnPb	IRL530
SILD	SiHL530

PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		$V_{DS}$	100	V	
Gate-Source Voltage	$V_{GS}$	± 10			
Continuous Drain Current	$V_{GS}$ at 5.0 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$		15	А	
	$T_C = 100 ^{\circ}C$	ID	11		
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	60	1		
Linear Derating Factor		0.59	W/°C		
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	290	mJ		
Repetitive Avalanche Current <sup>a</sup>	I <sub>AR</sub>	15	Α		
Repetitive Avalanche Energy <sup>a</sup>		E <sub>AR</sub>	8.8	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	$P_{D}$	88	W	
Peak Diode Recovery dV/dtc	dV/dt	5.5	V/ns		
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C		
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>		
Mounting Torque	6-32 or M3 screw		10	lbf ⋅ in	
	0-32 OF IVIS SCIEW		1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD}$  = 25 V, starting  $T_J$  = 25 °C, L = 1.9 mH,  $R_g$  = 25  $\Omega$   $I_{AS}$  = 15 A (see fig. 12).
- c.  $I_{SD} \le 15$  A,  $dI/dt \le 140$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_J \le 1\bar{7}5$  °C.
- d. 1.6 mm from case.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.7	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		<u>.</u>					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.14	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		1.0	-	2.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 10		-	-	± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V		-	-	25	μΑ
		$V_{DS} = 80 \text{ V}, V_{0}$	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C		-	250	
Drain-Source On-State Resistance	_	V <sub>GS</sub> = 5.0 V	I <sub>D</sub> = 9.0 A <sup>b</sup>	-	-	0.16	Ω
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.0 V	I <sub>D</sub> = 7.5 A <sup>b</sup>	-	-	0.22	
Forward Transconductance	9fs	$V_{DS} = 50 \text{ V}, I_D = 9.0 \text{ A}^b$		6.4	-	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ f = 1.0 MHz, see fig. 5		-	930	-	pF
Output Capacitance	C <sub>oss</sub>			-	250	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	57	-	
Total Gate Charge	Qg		$V_{GS} = 5.0 \text{ V}$ $I_{D} = 15 \text{ A}, V_{DS} = 80 \text{ V},$ see fig. 6 and 13b	-	-	28	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 5.0 V		-	-	3.8	
Gate-Drain Charge	Q <sub>gd</sub>	1	goo ng. o ana ro	-	-	14	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 50 V, $I_{D}$ = 15 A, $R_{g}$ = 12 $\Omega$ , $R_{D}$ = 32 $\Omega$ , see fig. 10 <sup>b</sup>		-	4.7	-	ns
Rise Time	t <sub>r</sub>			-	100	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	22	-	
Fall Time	t <sub>f</sub>			-	48	-	
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal Source Inductance	L <sub>S</sub>			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s	•					-
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	- A
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	60	
Body Diode Voltage	$V_{SD}$	$T_{J} = 25  ^{\circ}\text{C},  I_{S} = 15  \text{A},  V_{GS} = 0  \text{V}^{\text{b}}$		-	=	2.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 15 A, dl/dt = 100 A/μs <sup>b</sup>		-	150	200	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	0.93	1.4	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and L <sub>D</sub> )				L <sub>D</sub> )	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %.



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

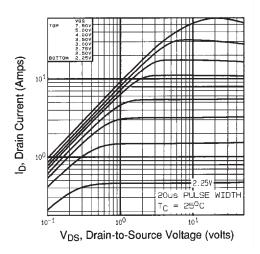


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

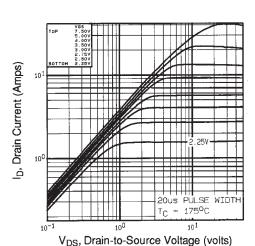


Fig. 2 - Typical Output Characteristics,  $T_C = 175$  °C

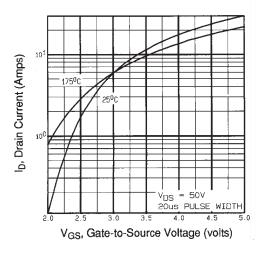


Fig. 3 - Typical Transfer Characteristics

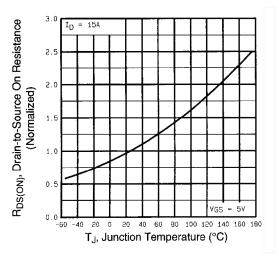


Fig. 4 - Normalized On-Resistance vs. Temperature



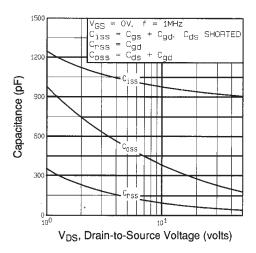


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

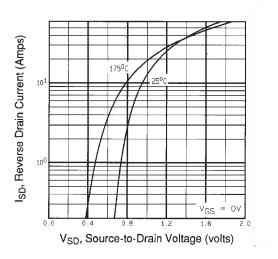


Fig. 7 - Typical Source-Drain Diode Forward Voltage

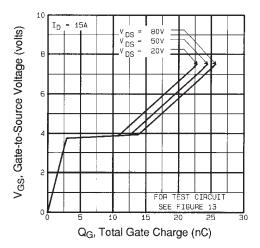


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

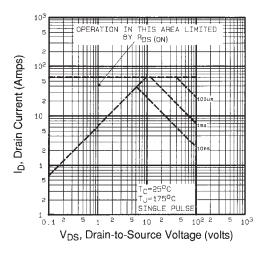


Fig. 8 - Maximum Safe Operating Area





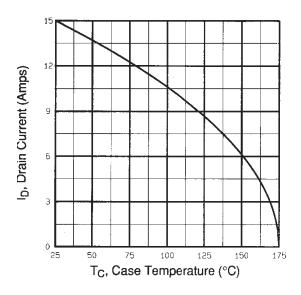


Fig. 9 - Maximum Drain Current vs. Case Temperature

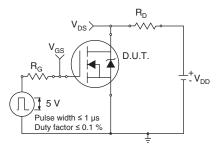


Fig. 10a - Switching Time Test Circuit

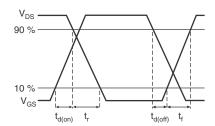


Fig. 10b - Switching Time Waveforms

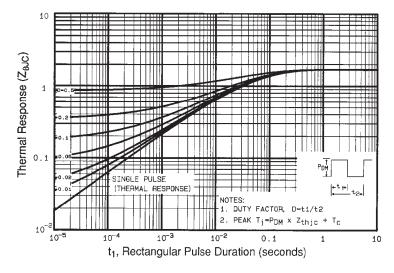


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



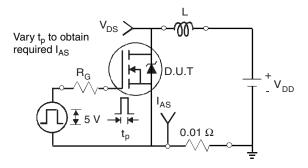


Fig. 12a - Unclamped Inductive Test Circuit

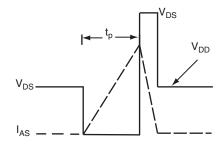


Fig. 12b - Unclamped Inductive Waveforms

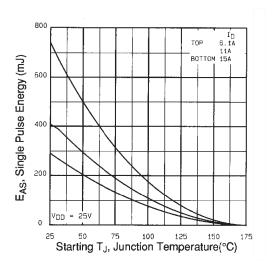


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

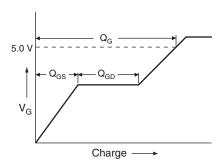


Fig. 13a - Basic Gate Charge Waveform

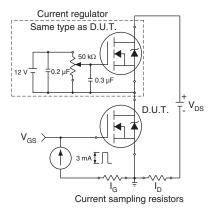
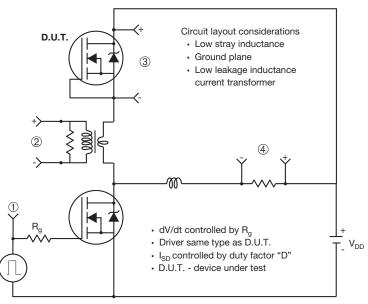


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



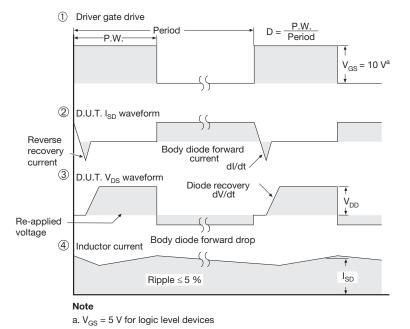


Fig. 14 - For N-Channel

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